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## (54) SILICON CONDENSER MICROPHONE AND MANUFACTURING METHOD

(75) Inventor: **Anthony D. Minervini**, Palos Hills, IL

(US)

(73) Assignee: Knowles Electronics LLC, Itasca, IL

(US)

(\*) Notice: Subject to any disclaimer, the term of this

patent is extended or adjusted under 35 U.S.C. 154(b) by 1136 days.

This patent is subject to a terminal dis-

claimer.

(21) Appl. No.: 11/741,881

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#### Related U.S. Application Data

- (60) Division of application No. 10/921,747, filed on Aug. 19, 2004, now Pat. No. 7,434,305, which is a continuation-in-part of application No. 09/886,854, filed on Jun. 21, 2001, now Pat. No. 7,166,910.
- (60) Provisional application No. 60/253,543, filed on Nov. 28, 2000.
- (51) Int. Cl. H01L 23/12 (2006.01) H01L 21/00 (2006.01) H04R 9/08 (2006.01)
- (52) **U.S. Cl.** ....... **257/704**; 257/724; 257/729; 257/730; 381/369; 438/26; 438/121

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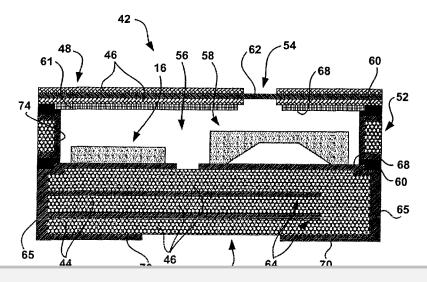
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Primary Examiner — Alonzo Chambliss (74) Attorney, Agent, or Firm — Dykema Gossett PLLC

#### (57) ABSTRACT

A silicon condenser microphone package and method for manufacture are disclosed. The silicon condenser microphone package includes a silicon condenser microphone die, a substrate comprising a conductive layer, and a cover having a conductive layer, where the conductive layers of the substrate and cover are electrically connected to form an electromagnetic interference shield for the silicon condenser microphone die. The method for manufacturing the silicon condenser microphone package involves placement of a plurality of silicon condenser microphone dies on a panel of printed circuit board material, placement of covers over each of the silicon condenser microphone dies, and then separating the panel into individual packages.

#### 26 Claims, 19 Drawing Sheets





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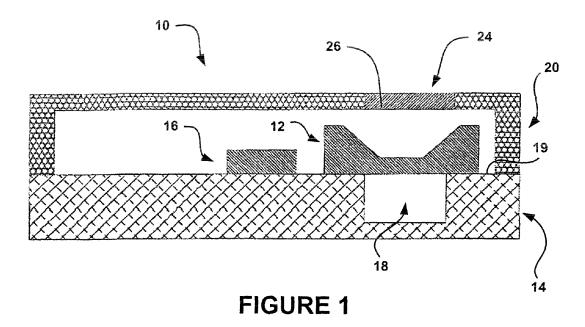
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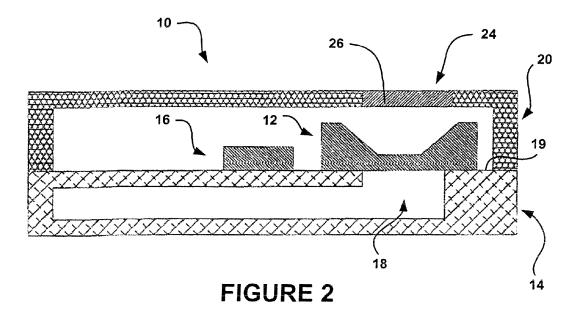
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